



HEL-00023-N1-GP



Application

LGA 1366/1356 (Socket B/B2) M3

Test result :

P (W)	Rca (°C/W)
130W	0.1437
150W	0.1418
180W	0.1384

Thermal and Mechanical Spec

Thermal performance for 130W/180W CPU

HSK Assembly Weight: 583 g

CPU Loading: 65 lbf

Safety



Component Specifications

Application System 4U Form Factor Active Solution

Material Aluminum Fin + Copper Base
+ Heat pipe 6 $\phi \times 3$

Dimension 88.2L $\times$ 88.2W $\times$ 112.15H mm
Fin Thick=0.4mm, Pitch=1.8mm, 45 fin

Thermal interface Material ShinEtsu 7783 (36 $\times$ 36 mm)

Fan Dimension ϕ 92 $\times$ 25.4 mm

Fan Bearing Type Two Ball

Fan Control PWM

Rate Voltage 12V

Life Time 70,000 hrs

Speed 5000 $\pm$ 10% rpm

Airflow 97.27~108.8 CFM (max)

Noise 59 dB(A) (max)

Connector Lead Wire: UL1061 AWG#26

Pin 1: black wire -----(-)

Pin 2: red wire -----(+)

Pin 3: yellow wire -----(F00)

Pin 4: blue wire -----(PWM)

Housing Molex 47054-1000 or Equivalent

Terminal Molex 2759T 08-50-0013 or Equivalent

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.